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Selected Papers from ICAM2016 and ICI2016

Guest Editor:

Prof. Dr. Chien-Hung Liu

Department of Mechanical Engineering, National Chung Hsing University, 250 Kuo Kuang Rd., Taichung 402, Taiwan

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closed (31 August 2017)

Message from the Guest Editor

Dear Colleagues,

This Special Issue will select the papers related to invention/innovation advanced manufacturing, especially smart manufacturing, from ICI2016 (2016 2nd International Conference on Inventions, http://sciforum.net/conference/ICI2016) and ICAM 2016 (2016 International Conference on Advanced Manufacturing, http://sciforum.net/conference/ICAM2016).

Smart manufacturing focuses on new and emerging technologies for industry 4.0. Papers with innovative ideas or research results in all aspects of advanced manufacture are also encouraged.

Prof. Dr. Chien-Hung Liu *Guest Editor*











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Editors-in-Chief

Prof. Dr. Chien-Hung Liu

Department of Mechanical Engineering, National Chung Hsing University, 250 Kuo Kuang Rd., Taichung 402, Taiwan

Prof. Dr. Shoou-Jinn Chang

Department of Electrical Engineering, National Cheng Kung University, Tainan 701, Taiwan

Message from the Editorial Board

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